

Notice of References Cited	Application/Control No. 09/785,006		Applicant(s)/Patent Under Reexamination SCHOENFELD, AARON	
	Examiner Evan Pert		Art Unit 2829	Page 1 of 2

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*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)
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	UU	Haghiri et al., Chapter 5 of on-line encyclopedia, "Smart Card Manufacturing: A Practical Guide" by John Wiley & Sons Ltd., Electronic ISBN 0-470-84609-7, pages 80-101.
	VV	Excerpt of Tables from SEMI M8-93, 4 pages downloaded from http://www.semimat.com/Test-semistandard .
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